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# TTM Technologies, Inc. Announces Upcoming Conference Participation

COSTA MESA, Calif., May 10, 2018 (GLOBE NEWSWIRE) -- TTM Technologies, Inc. (NASDAQ:TTMI), a leading global printed circuit board (PCB) manufacturer, today announced that members of its management team will present at the following investor conferences:

- The J.P Morgan Global Technology, Media, and Communications Conference in Boston at the Westin Boston Waterfront Hotel on May 17<sup>th</sup>, 2018 at 11:20am Eastern Time;
- The Barclays High Yield Bond and Syndicated Loan Conference in Colorado Springs at the Broadmoor Hotel on May 22<sup>th</sup>, 2018 at 3:25 pm Mountain Time; and
- The Stifel Cross Sector Insight Conference in Boston at the InterContinental Hotel on June 12<sup>th</sup>, 2018 at 3:00pm Eastern Time.

In addition, the company will be hosting an Analyst and Investor Day on Thursday, May 24<sup>th</sup> at the Westin Grand Central Hotel in New York City at 10:00am Eastern time.

All presentations will be webcast live on the company's website, [www.ttm.com](http://www.ttm.com), and a replay will be accessible for a limited time following the events.

## About TTM

TTM Technologies, Inc. is a leading global printed circuit board manufacturer, focusing on quick-turn and technologically advanced PCBs, backplane assemblies and electro-mechanical solutions. TTM stands for time-to-market, representing how TTM's time-critical, one-stop manufacturing services enable customers to shorten the time required to develop new products and bring them to market. Additional information can be found at [www.ttm.com](http://www.ttm.com).

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